

Sn62/Pb36/Ag2 Solder Spheres for BGAs

Product Highlights

Chip Quik® BGA solder spheres are manufactured from virgin materials to meet or exceed the requirements of building or repairing BGA packages. Chip Quik® BGA solder spheres also exceed both the IPC and MIL standards for purity levels and size tolerances. Nominal sizes are available from 8 to 30 mil (0.2 to 0.76mm).



Product Specifications

Part Number	Alloy	Melting Point	Diameter	Quantity (by weight)
CQ-SS-623602-0.65MM-25000	Sn62/Pb36/Ag2	179°C (354°F)	0.65mm	25,000

Shelf Life: >24 months

Test Results

Test J-STD-004 or other requirements as stated	Test Requirement	Result
Conflict Minerals Compliance	Electronic Industry Citizenship Coalition (EICC)	Compliant
REACH Compliance	Articles 33 and 67 of Regulation (EC) No 1907/2006	Contains Lead (Pb) CAS# 7439-92-1 No other SVHC present

Conforms to the following Industry Standards:

J-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders): Yes
RoHS 3 Directive (EU) 2015/863: No